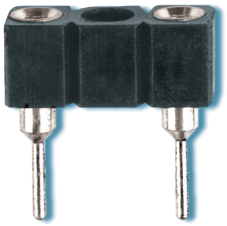
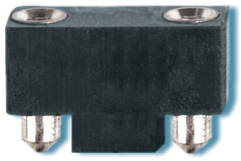
562/564 Series

Circuit Board Mount Blocks for TE5/TR5 Type Fuses



562 Series Holder



564 Series Holder

Additional Information

Resources 562 Series

Accessories 562 Series

Samples 562 Series

Resources 564 Series

Accessories 564 Series

Samples 564 Series

Product Characteristics

	562 Series	564 Series
Compatible Fuses	TR5/TE5	
Materials	Block: Black Thermoplastic, UL94 V-0 PET	
	Terminals: Copper alloy; solderable tinned	
Electrical Data (23°C)	Rated Voltage: 250V	
	Max. Current/Power: 6.3A/1.6W	
Mounting	PC Board, 5.08mm pin spacing	PC Board, 5.08mm pad spacing
Minimum Cross Section	Conducting path - 0.1mm²	Conducting path - 0.1mm²
Unit Weight	0.12g	0.44g
Ambient Temperature	- 40°C to + 85°C	

Ordering Information

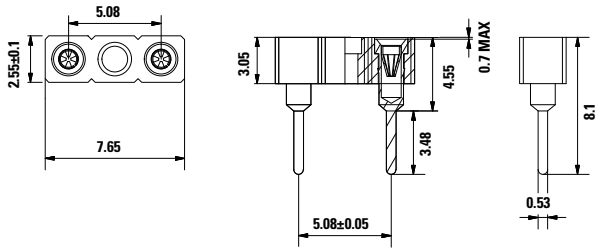
Ordering Number	Circuit Board Mounting	Packaging
56200001009	Thru-Hole	1000 (Bulk pack)
56400001009	Surface Mount	1500 (Tape /Reel)

Agency Approvals

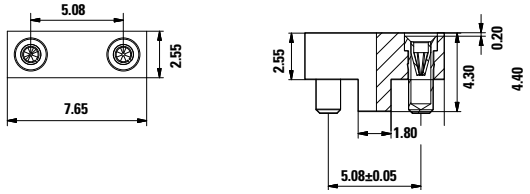
Agency	Agency File Number	
	562 Series	564 Series
	E14721	E14721

Dimensions units in mm

562 Series Holder



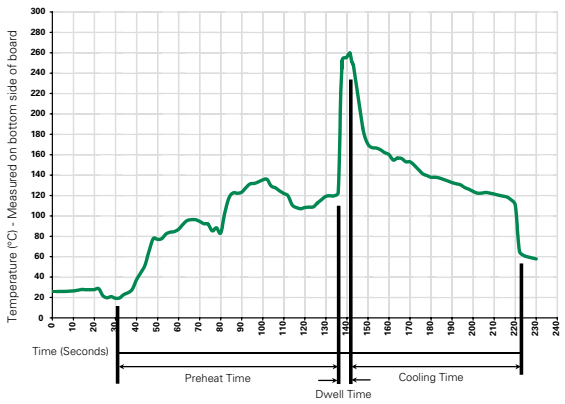
564 Series Holder



Revised: GD. 05/04/21

562/564 Series
Circuit Board Mount Blocks for TE5/TR5 Type Fuses

Soldering Parameters - Wave Soldering



Recommended Process Parameters:

Wave Parameter	Lead-Free Recommendation
Preheat: (Depends on Flux Activation Temperature)	(Typical Industry Recommendation)
Temperature Minimum:	100°C
Temperature Maximum:	150°C
Preheat Time:	60-180 seconds
Solder Pot Temperature:	260°C Maximum
Solder Dwell Time:	2-5 seconds

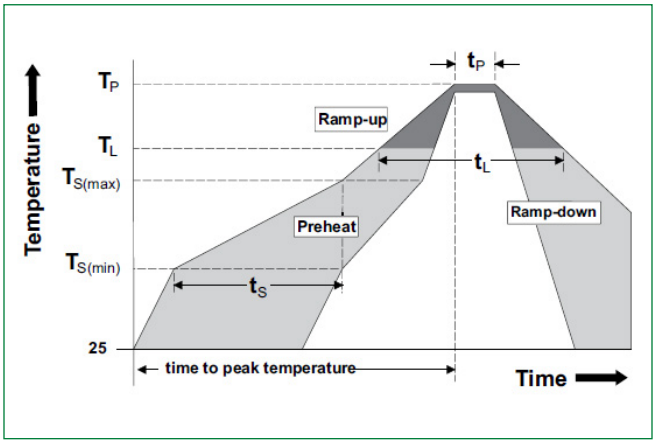
Recommended Hand-Solder Parameters:

Solder Iron Temperature: 350°C +/- 5°C
Heating time: 5 seconds max

Note: These devicess are not recommended for IR and Convection Reflow process

Soldering Parameters - Reflow Soldering

Reflow Condition		Pb - Free assembly
Number of allowed reflow cycles		3
Pre Heat	**-Temperature Min ($T_{s(min)}$)**	150°C
	-Temperature Max ($T_{s(max)}$)	200°C
	-Time (Min to Max) (t_s)	60 - 120 Secs.
Average ramp up rate (Liquidus Temp (T_L) to peak		5°C/second max.
$T_{s(max)}$ to T_L - Ramp-up Rate		5°C/second max.
Reflow	**-Temperature (T_L) (Liquidus)**	217°C
	-Temperature (t_L)	60 - 150 seconds
Peak Temperature (T_P)		240$^{+/-5}$ °C
Time within 5oC of actual peak Temperature (t_p)		30 secs. max.
Ramp-down Rate		5°C/second max.
Time 25°C to peak Temperature (T_P)		8 minutes max.
Do not exceed		245°C



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